

P-Channel Enhancement Mode Power MOSFET

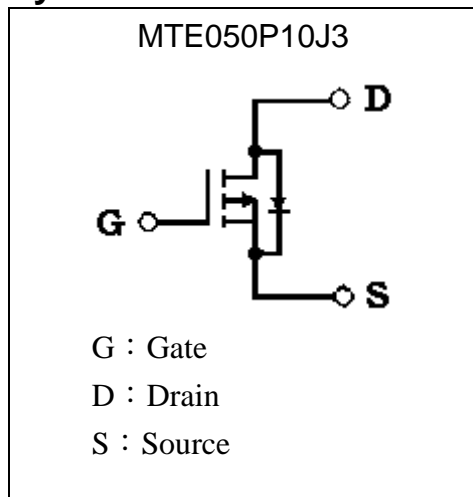
MTE050P10J3

BV_{DSS}	-100V
I_D@V_{GS}=-10V, T_C=25°C	-28A
I_D@V_{GS}=-10V, T_C=100°C	-17.7A
I_D@V_{GS}=-10V, T_A=25°C	-5.1A
I_D@V_{GS}=-10V, T_A=70°C	-4.1A
R_{DS(ON)}@V_{GS}=-10V, I_D=-14A	50 mΩ (typ)

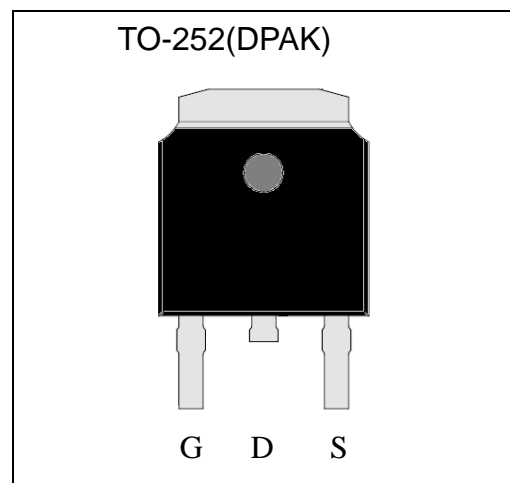
Features

- Single Drive Requirement
- Low On-resistance
- Fast switching Characteristic
- Pb-free lead plating and halogen-free package

Symbol

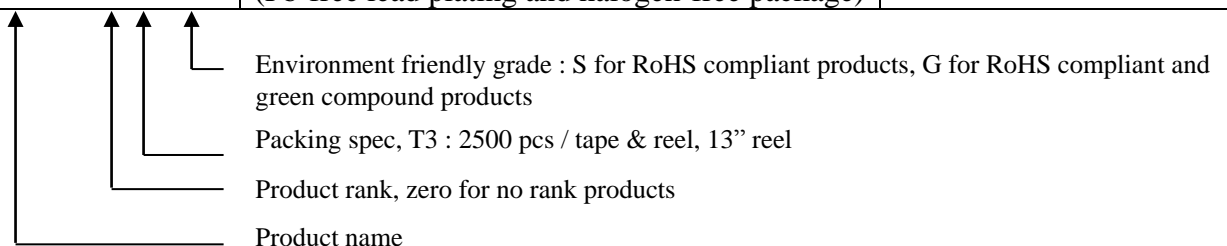


Outline



Ordering Information

Device	Package	Shipping
MTE050P10J3-0-T3-G	TO-252 (Pb-free lead plating and halogen-free package)	2500 pcs / Tape & Reel



**Absolute Maximum Ratings** (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	-100	V
Gate-Source Voltage		V _{GS}	±20	
Continuous Drain Current @ V _{GS} =-10V, T _C =25°C (Note1)		I _D	-28	A
Continuous Drain Current @ V _{GS} =-10V, T _C =100°C (Note1)			-17.7	
Continuous Drain Current @ V _{GS} =-10V, T _A =25°C (Note4)			-5.1	
Continuous Drain Current @ V _{GS} =-10V, T _A =70°C (Note4)			-4.1	
Pulsed Drain Current (Note3)		I _{DM}	-112	
Power Dissipation	T _C =25°C (Note1)	P _D	69	W
	T _C =100°C (Note1)		27.6	
	T _A =25°C (Note2)	P _{DSM}	2.5	
	T _A =70°C (Note2)		1.6	
Single Pulse Avalanche Energy @ L=1mH, I _{AS} =-24A, V _{DD} =-25V (Note5)		E _{AS}	288	mJ
Single Pulse Avalanche Current		I _{AS}	-24	A
Operating Junction and Storage Temperature		T _j , T _{stg}	-55~+150	°C

Thermal Data

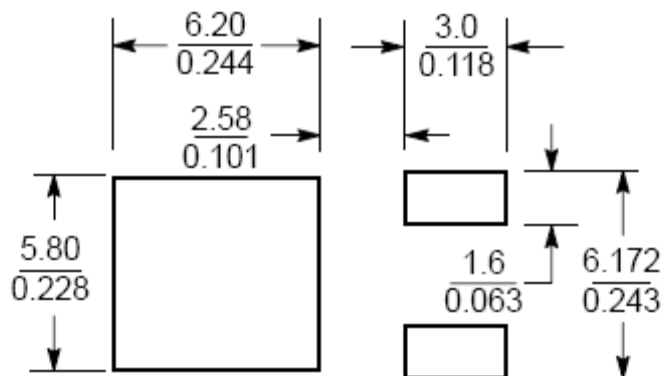
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{th,j-c}	1.8	°C/W
Thermal Resistance, Junction-to-ambient, max (Note2)	R _{th,j-a}	50	
Thermal Resistance, Junction-to-ambient, max (Note4)		90	

- Note : 1.The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
2. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with T_A=25°C. The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.
4. When mounted on the minimum pad size recommended (PCB mount), t≤10s.
5. 100% tested by conditions of L=1mH, I_D=-10A, V_{GS}=-10V, V_{DD}=-25V

Characteristics (T_j=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-100	-	-	V	V _{GS} =0V, I _D =-1mA
ΔBV _{DSS} /ΔT _j	-	-0.09	-	V/°C	Reference to 25°C, I _D =-250μA
V _{GS(th)}	-2	-	-3.5	V	V _{DS} = 10V, I _D =-1mA
G _{FS}	-	32.8	-	S	V _{DS} = -5V, I _D =-20A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	-1	μA	V _{DS} = -100V, V _{GS} = 0V
I _{DSS}	-	-	-25		V _{DS} = -80V, V _{GS} = 0V, T _j =70°C
*R _{DS(ON)}	-	50	70	mΩ	V _{GS} = -10V, I _D =-14A
Dynamic					
*Q _g	-	33.5	-	nC	V _{DS} =-50V, I _D =-14A, V _{GS} =-10V
*Q _{gs}	-	7.6	-		
*Q _{gd}	-	11.5	-		
*t _{d(ON)}	-	20.8	-	ns	V _{DS} =-50V, I _D =-1A, V _{GS} =-10V, R _G =6Ω
*t _r	-	18	-		
*t _{d(OFF)}	-	73.8	-		
*t _f	-	63.8	-		
C _{iss}	-	1875	-	pF	V _{GS} =0V, V _{DS} =-30V, f=1MHz
C _{oss}	-	193	-		
C _{rss}	-	86	-		
R _g	-	4.7	-		
Source-Drain Diode					
*I _S	-	-	-28	A	
*V _{SD}	-	-0.9	-1.5	V	I _S =-28A, V _{GS} =0V
*t _{rr}	-	30	-	ns	I _F =-20A, V _{GS} =0V, dI _F /dt=-100A/μs
*Q _{rr}	-	43	-	nC	

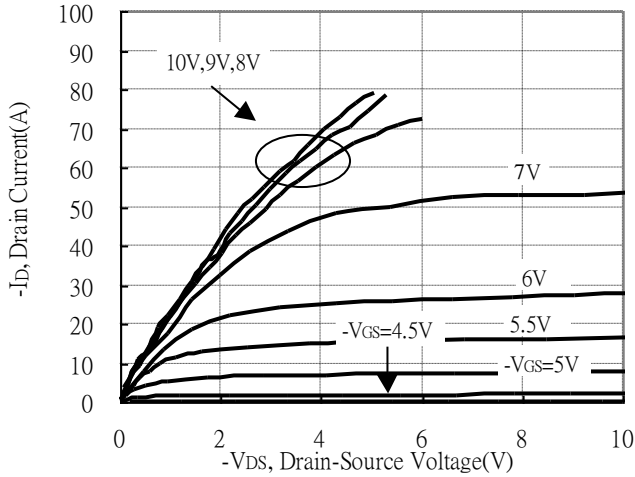
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended soldering footprint

 Unit ($\frac{\text{mm}}{\text{inch}}$)

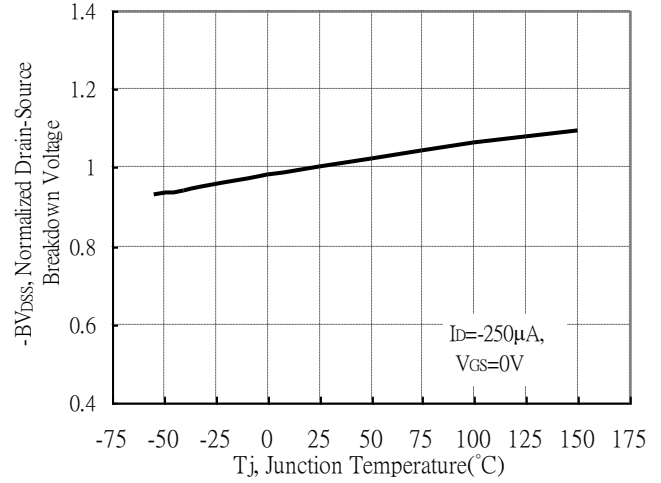


Typical Characteristics

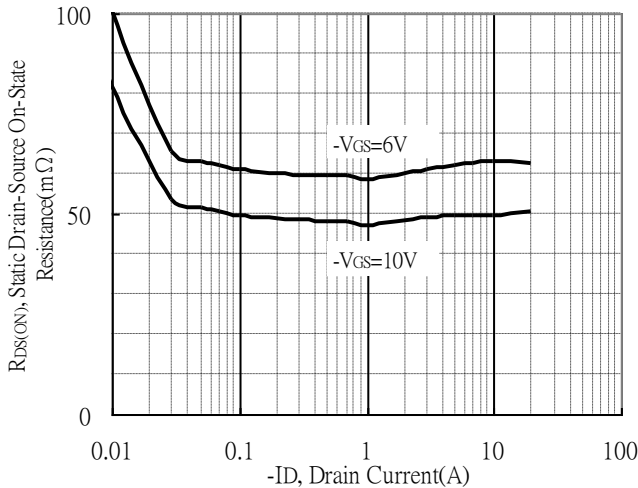
Typical Output Characteristics



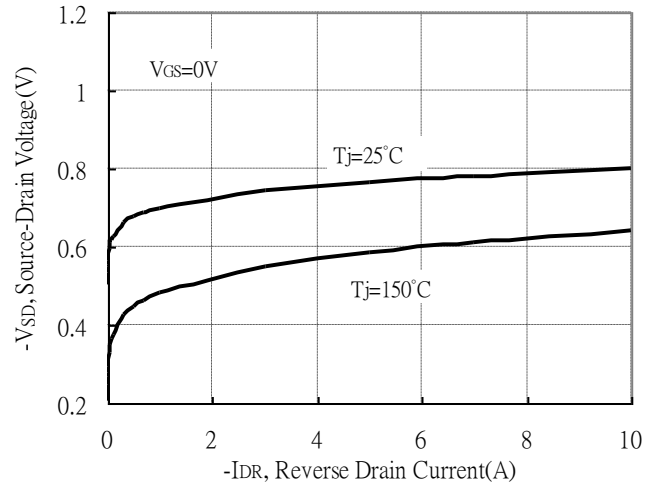
Brekdown Voltage vs Ambient Temperature



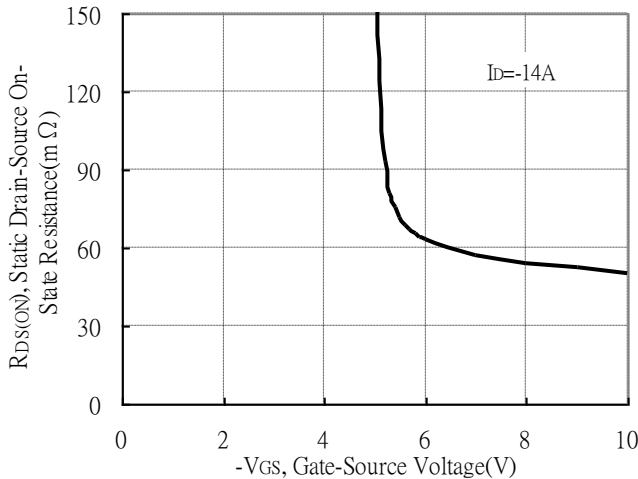
Static Drain-Source On-State resistance vs Drain Current



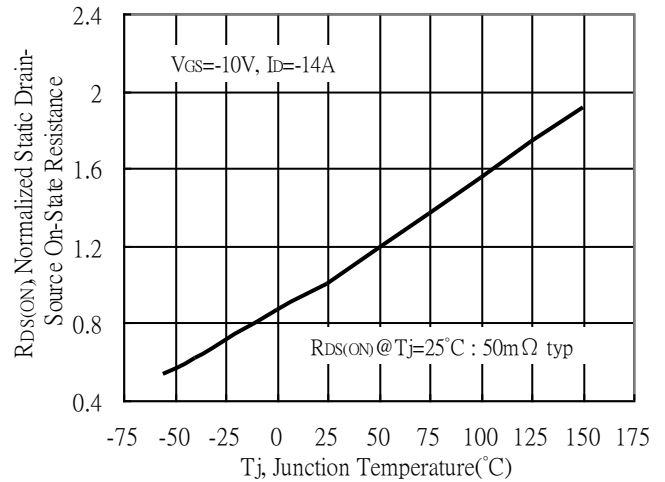
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

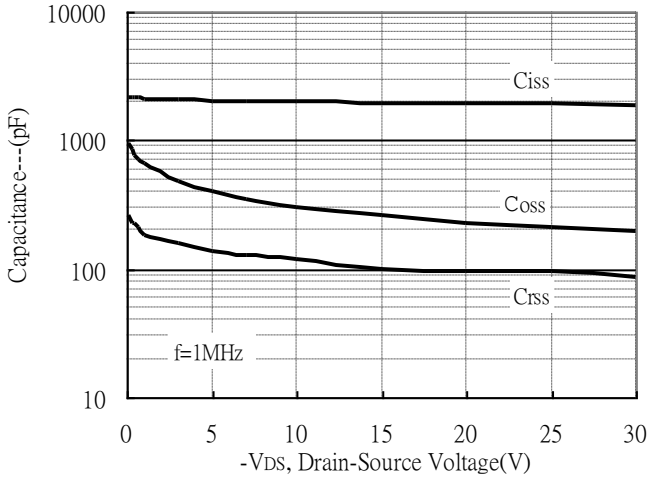


Drain-Source On-State Resistance vs Junction Teperature

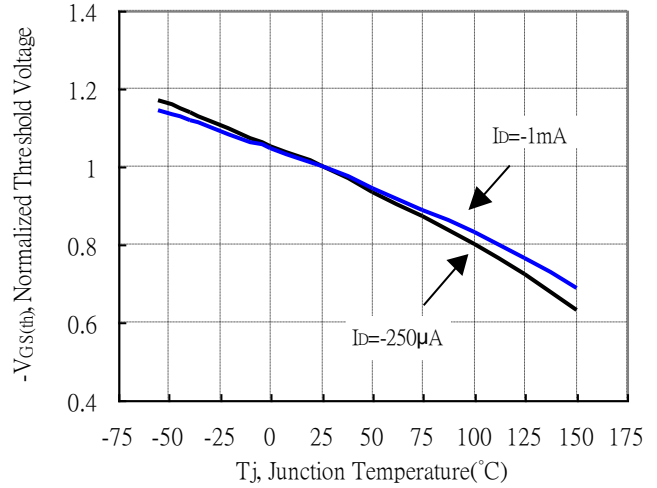


Typical Characteristics(Cont.)

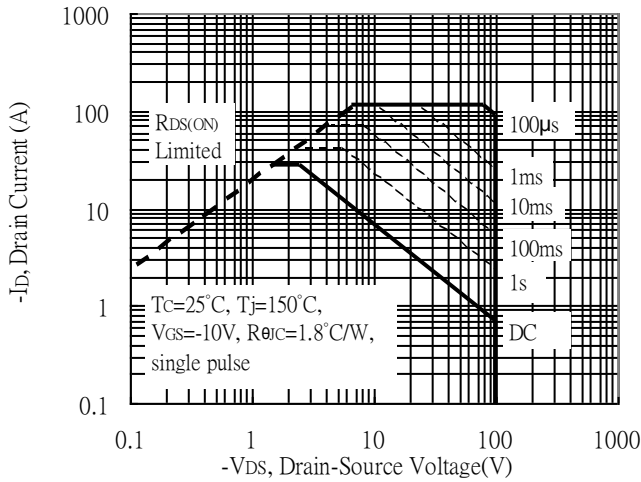
Capacitance vs Drain-to-Source Voltage



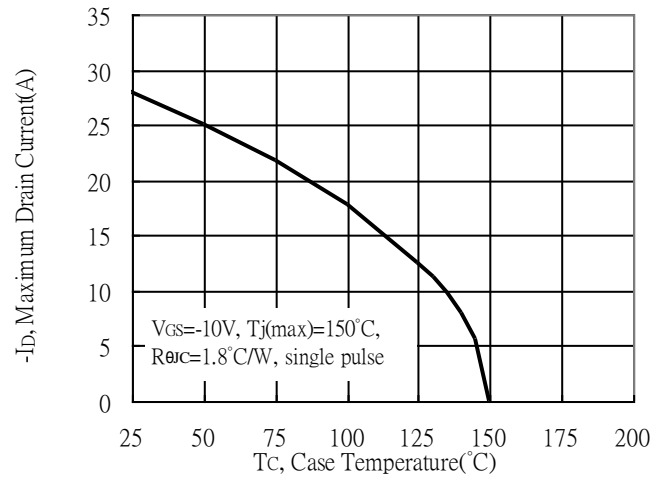
Threshold Voltage vs Junction Temperature



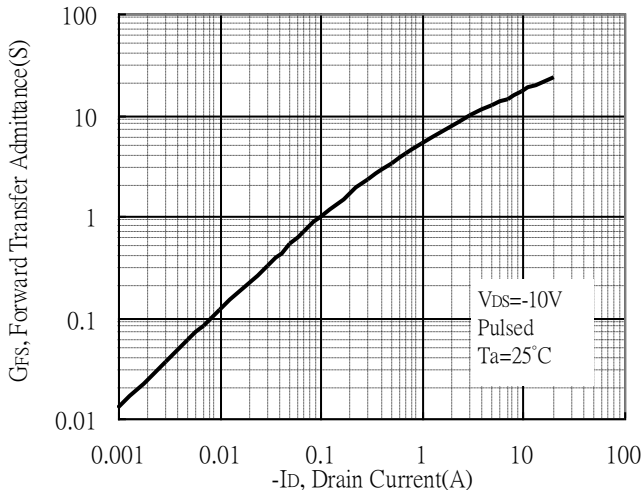
Maximum Safe Operating Area



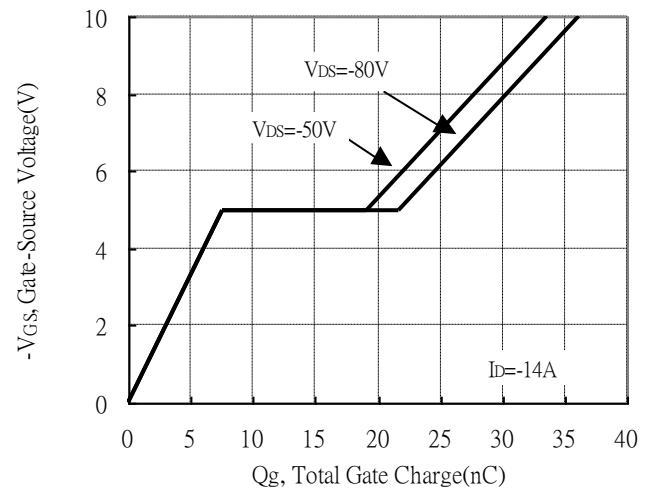
Maximum Drain Current vs Case Temperature



Forward Transfer Admittance vs Drain Current



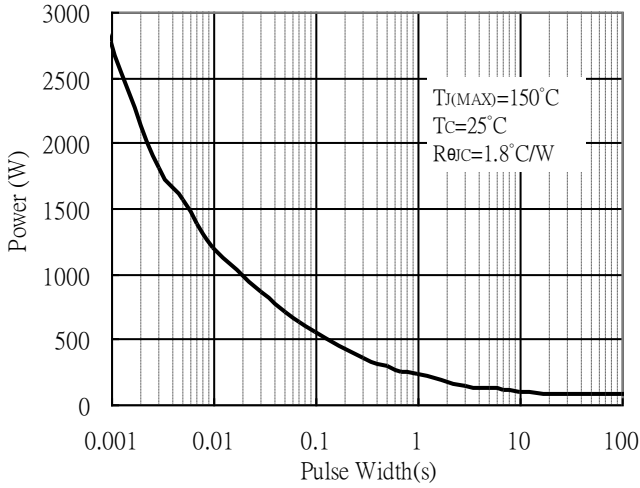
Gate Charge Characteristics



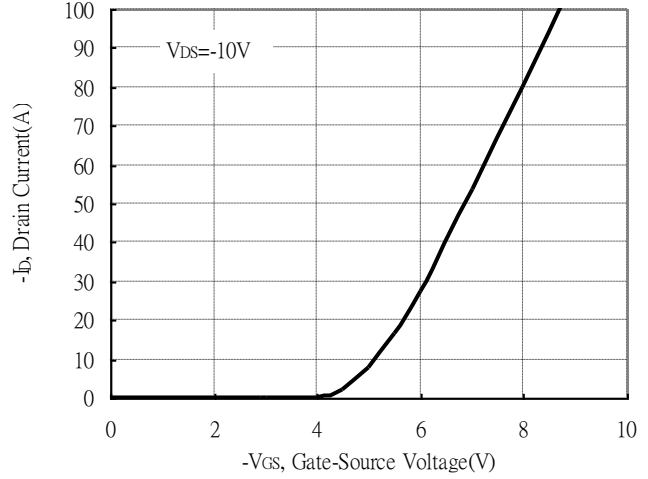


Typical Characteristics(Cont.)

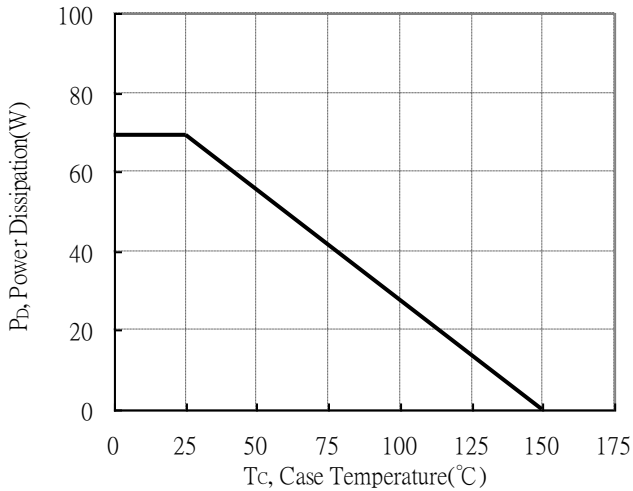
Single Pulse Power Rating, Junction to Case



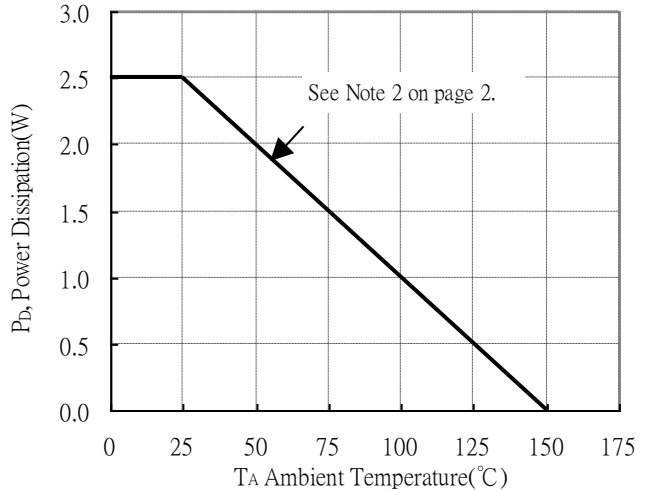
Typical Transfer Characteristics



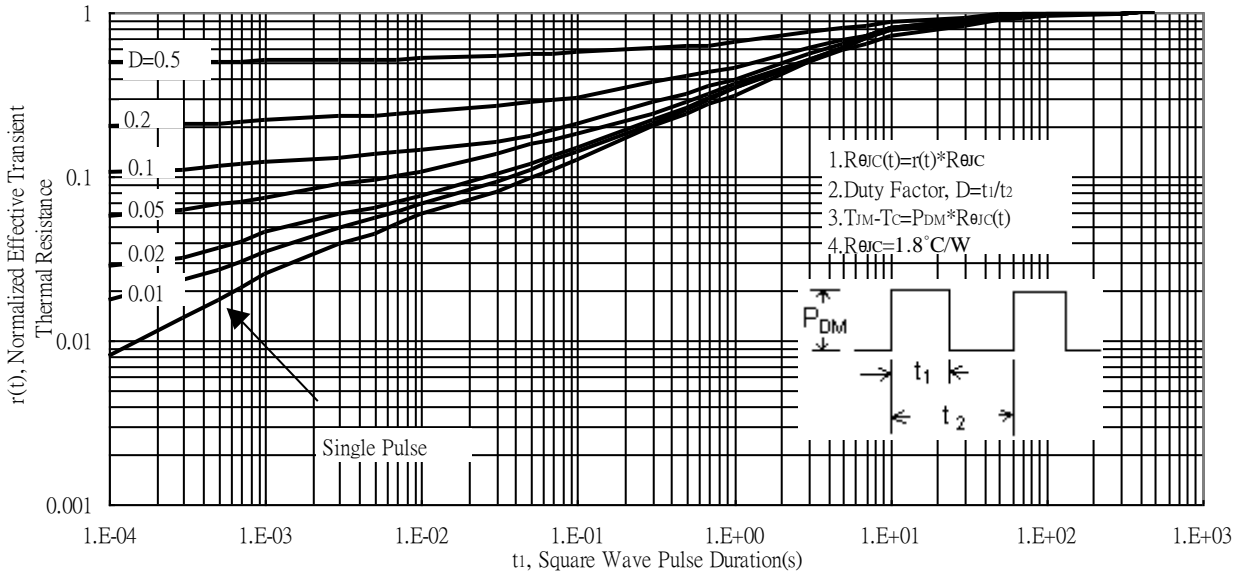
Power Derating Curve



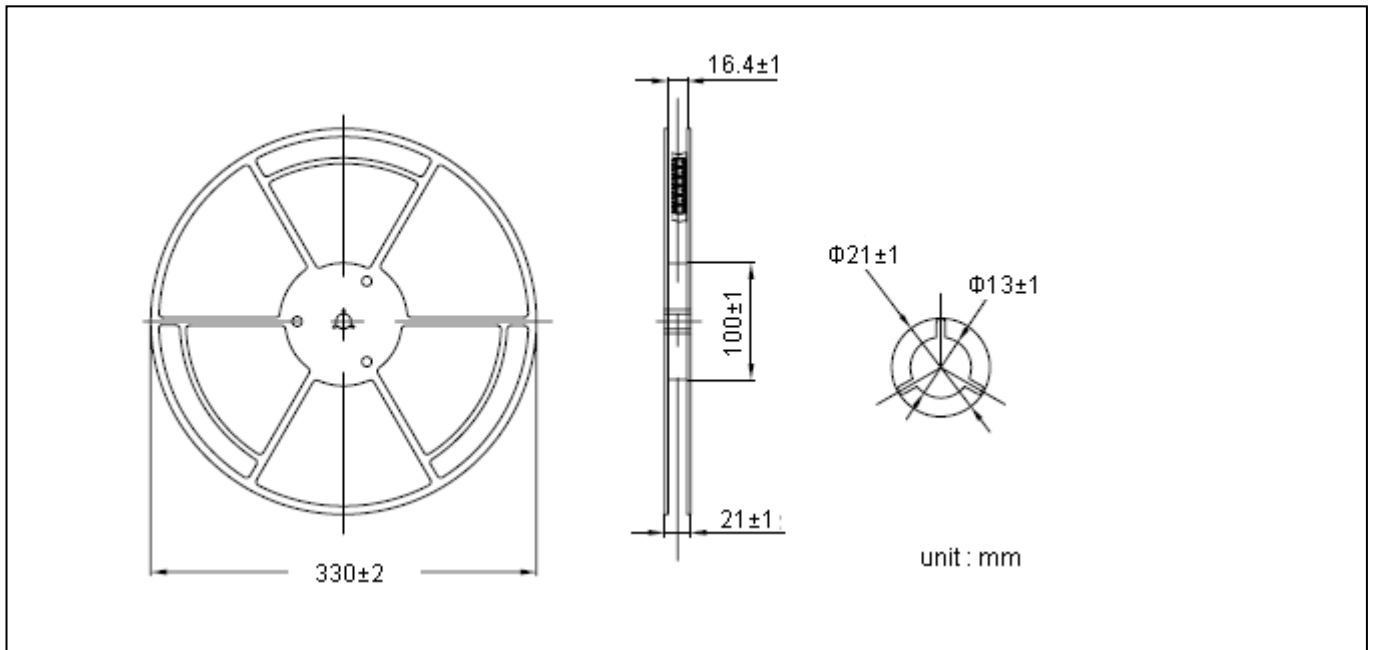
Power Derating Curve



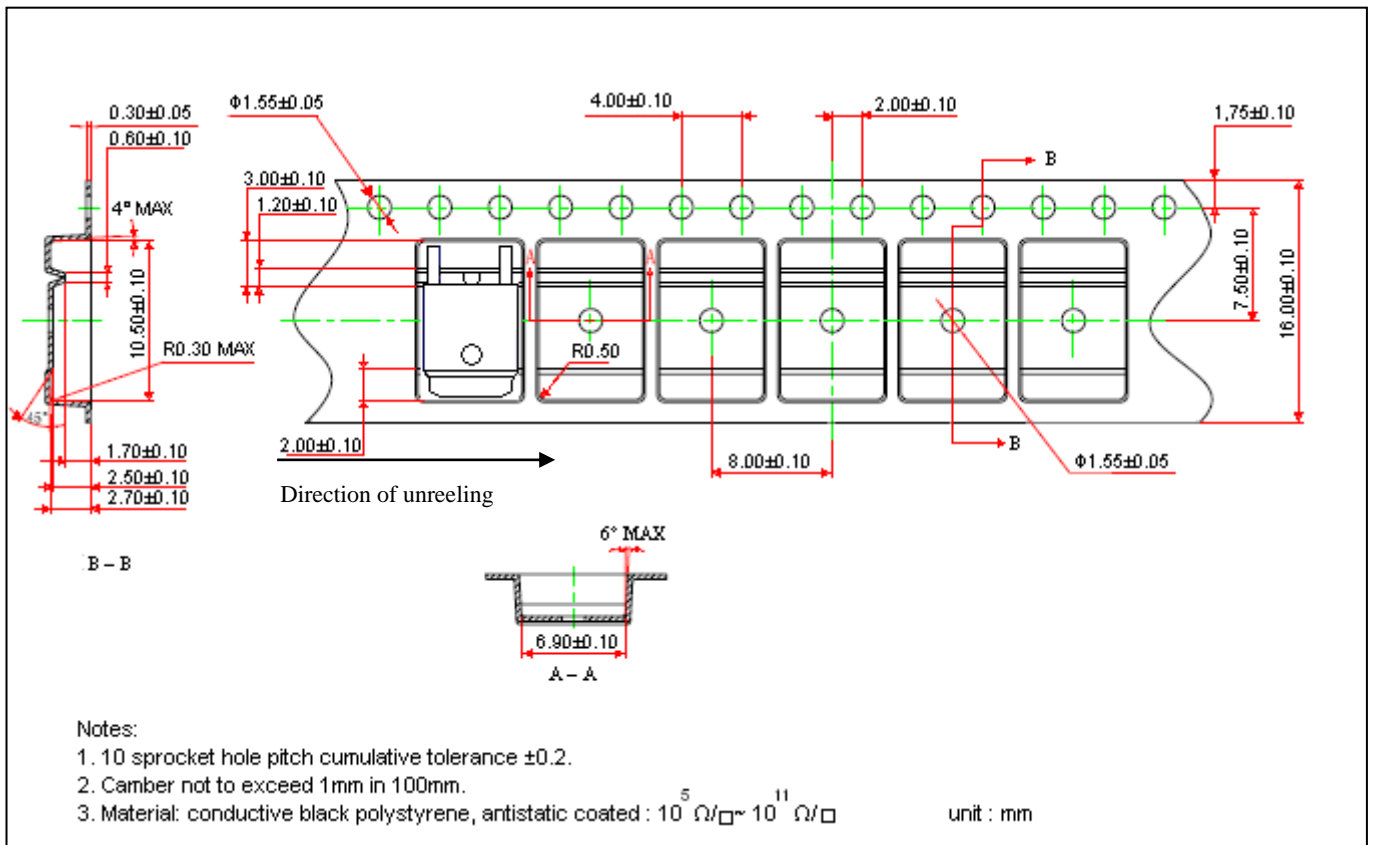
Transient Thermal Response Curves



Reel Dimension



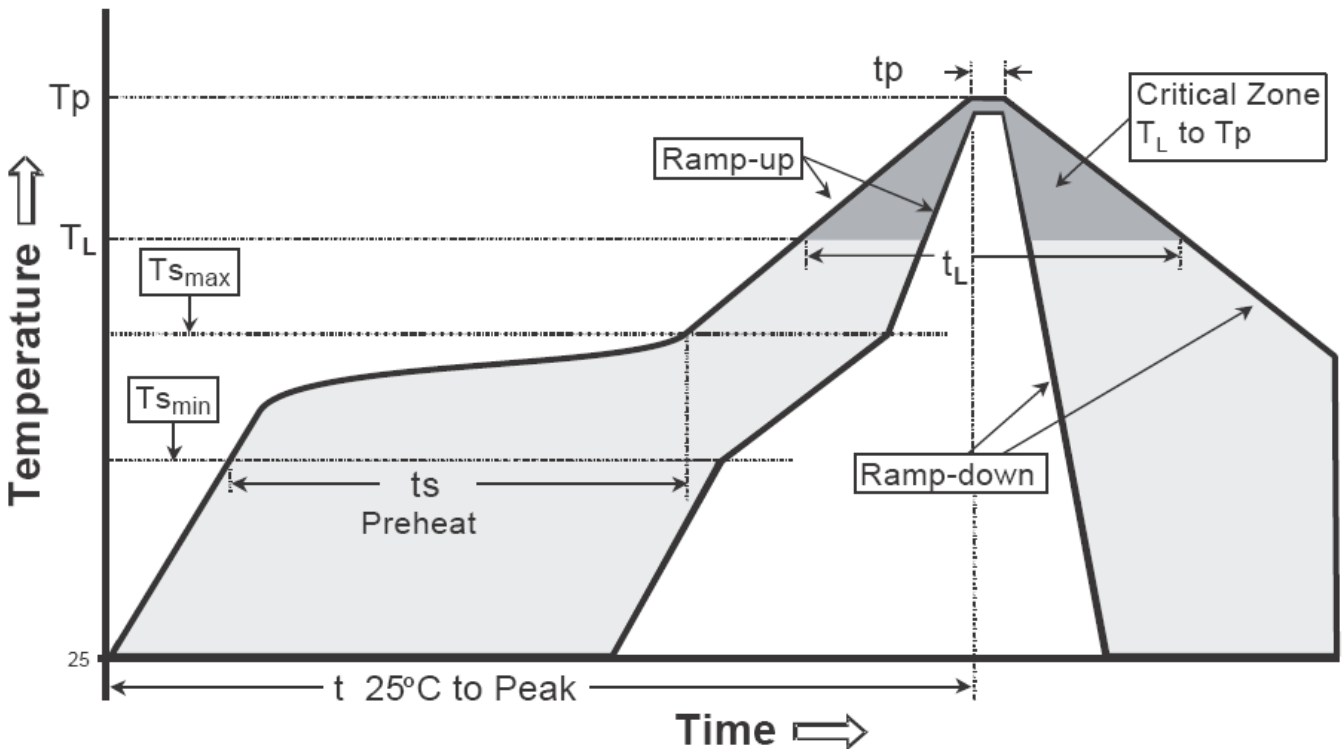
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

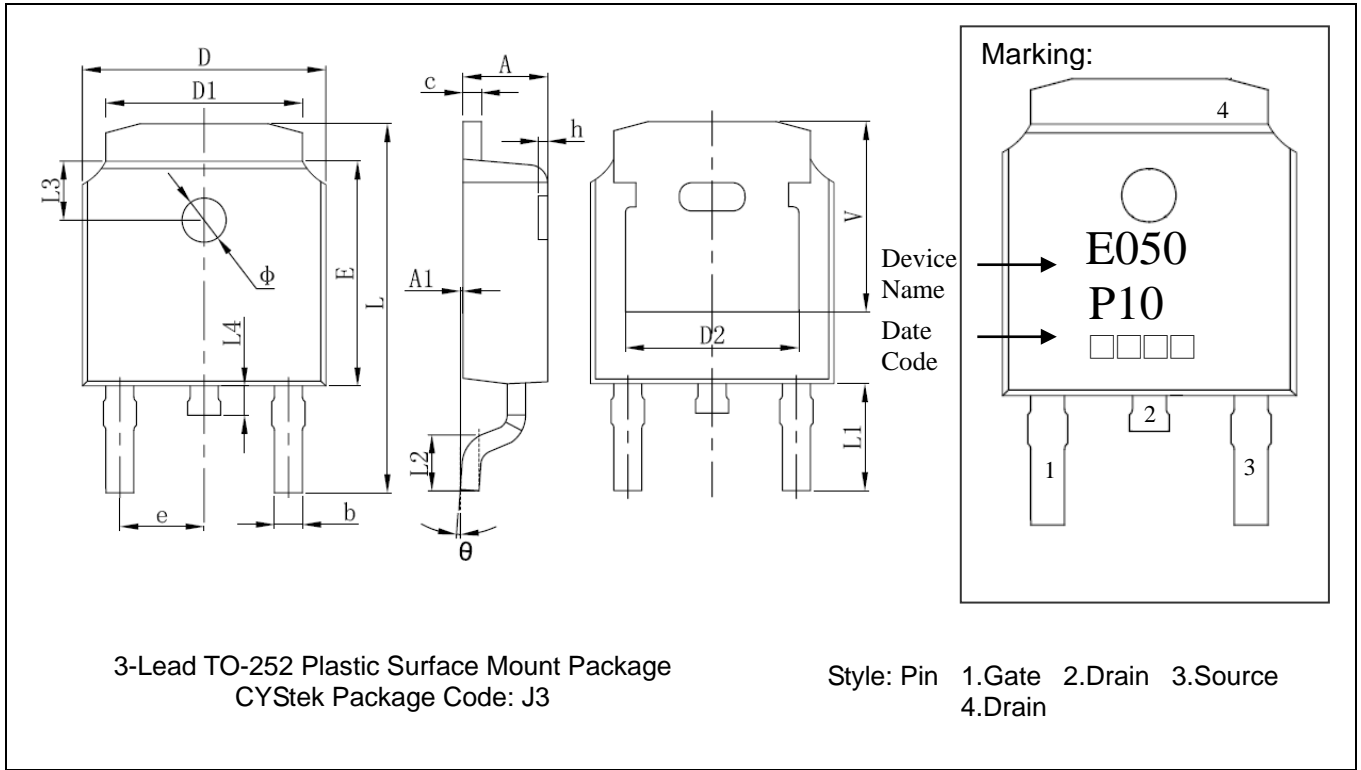
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t _p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	L	0.382	0.406	9.712	10.312
A1	0.000	0.005	0.000	0.127	L1	0.114	REF	2.900	REF
b	0.025	0.030	0.635	0.770	L2	0.055	0.067	1.400	1.700
c	0.018	0.023	0.460	0.580	L3	0.063	REF	1.600	REF
D	0.256	0.264	6.500	6.700	L4	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	Φ	0.043	0.051	1.100	1.300
D2	0.190	REF	4.830	REF	θ	0°	8°	0°	8°
E	0.236	0.244	6.000	6.200	h	0.000	0.012	0.000	0.300
e	0.086	0.094	2.186	2.386	v	0.207	REF	5.250	REF

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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